

**Statement on non-use of HBCDD & Phthalates (DEHP, BBP,  
DBP, DINP, DNOP, DIBP and DIDP)  
In Texas Instruments (TI) Semiconductor Products**

Texas Instruments continues to actively monitor regulatory requirements for new and proposed regulations that may restrict the use of additional substances in electronic products. An update to the EU RoHS Directive, (EU) 215/863, was released on 31 March 2015 restricting the use of 4 Phthalates in electrical and electronic equipment, these Phthalates are Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) and Diisobutyl phthalate (DIBP). The law will come into effect on 22 July 2019.

The 4 Phthalates have already been evaluated with TI's internal tracking systems and have been determined to not be contained in TI's finished IC products. This database is developed from full material (homogeneous) reporting required from our suppliers for each material set approved for production. TI will have additional 3<sup>rd</sup> party test reports for materials used in IC products as further due diligence proof by late-2018 to support the 22 July 2019 effective date.

Verifying materials contained within finished TI IC products can be made online using the [www.ti.com/productcontent](http://www.ti.com/productcontent) web tool. As laws are released, any new testing requirements will take approximately 18 months to pass through the supply chain for applicable material sets.

Sincerely,



Mark Frimann  
SC Product Stewardship Management  
SC Quality – Texas Instruments

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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